

IN THE CLAIMS

Please substitute the claim set in the appendix entitled "Clean Version of Pending Claims" for the previously pending claim set. The substitute claim set reflects the cancellation of claims 20, 24-25, 29-30, and 34; the amendment of previously pending claims 17, 19, 21, 26, and 31; and the addition of new claims 35-46.

The specific amendments to individual claims are detailed in the following marked-up set of claims.

17. (Amended) An electronic package substrate comprising:
a thin, flexible, electrically insulating film having a conductor region [adapted] to mount an integrated circuit;
a plurality of traces within the film, including within [in] the conductor region; and
a plurality of lands on a surface of the film and coupled to the traces, wherein the lands are to mount corresponding pads of the integrated circuit in a ball grid array.

18. The electronic package substrate recited in claim 17, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

19. (Amended) The electronic package substrate recited in claim 17, wherein the film comprises a plurality of layers, each comprising a plurality of traces [in the conductor region].

✓ 20. (Canceled) The electronic package substrate recited in claim 17, wherein the lands are arranged in a ball grid array.

21. (Amended) An electronic package comprising:
an electrically insulating film having a thickness in the range of approximately .15 to .90 millimeters, the film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands coupled to the traces; and
an integrated circuit [electronic component] having a plurality of pads coupled to the

plurality of lands in a ball grid array.

22. The electronic package recited in claim 21, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

23. The electronic package recited in claim 21, wherein the film comprises a plurality of layers, each comprising a plurality of traces in the conductor region, and wherein each layer has a thickness within the range of approximately .15 to .30 millimeters.

✓ 24. (Canceled) The electronic package recited in claim 21, wherein the lands are arranged in a ball grid array.

✓ 25. (Canceled) The electronic package recited in claim 21, wherein the electronic component comprises an integrated circuit.

26. (Amended) An electronic system having [comprising] at least one electronic assembly comprising:

a thin, flexible, electrically insulating film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands coupled to the traces; and

an integrated circuit [electronic component] having a plurality of pads coupled to the plurality of lands in a ball grid array.

27. The electronic system recited in claim 26, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

28. The electronic system recited in claim 26, wherein the film comprises a plurality of layers, each comprising a plurality of traces in the conductor region.

✓ 29. (Canceled) The electronic system recited in claim 26, wherein the lands are arranged in a ball grid array.

✓ 30. (Canceled) The electronic system recited in claim 26, wherein the electronic component comprises an integrated circuit.

31. (Amended) A data processing system comprising:
a bus coupling components in the data processing system;
a display coupled to the bus;
a memory coupled to the bus; and
a processor coupled to the bus and comprising an electronic assembly including,
a thin, flexible electrically insulating film having a conductor region, a plurality of traces in the conductor region, and a plurality of lands coupled to the traces; and
an integrated circuit having a plurality of pads coupled to the plurality of lands in a ball grid array.

32. The data processing system recited in claim 31, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

33. The data processing system recited in claim 31, wherein the film comprises a plurality of layers, each comprising a plurality of traces in the conductor region.

✓ 34. (Canceled) The data processing system recited in claim 31, wherein the lands are arranged in a ball grid array.

Please add new claims 35-46 as follows:

35. (New) The electronic package substrate recited in claim 17, wherein the film comprises one or more vias coupled to corresponding ones of the traces.

36. (New) The electronic package substrate recited in claim 19, wherein the film comprises one or more vias to couple traces within different layers.
37. (New) A package substrate comprising:
a thin, flexible, electrically insulating film having a conductor region to mount an integrated circuit;
a plurality of traces, at least some of which are within the conductor region;
one or more vias within the film and coupled to corresponding ones of the traces; and
a plurality of lands on a surface of the film and coupled to the traces, wherein the lands are to mount corresponding pads of the integrated circuit.
38. (New) The package substrate recited in claim 37, wherein the film is formed of material from the group comprising a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.
39. (New) The package substrate recited in claim 37, wherein the film comprises a plurality of layers, each comprising a plurality of traces.
40. (New) The package substrate recited in claim 39, wherein the one or more vias couple traces within different layers.
41. (New) The electronic package recited in claim 21, wherein the film comprises one or more vias coupled to corresponding ones of the traces.
42. (New) The electronic package recited in claim 23, wherein the film comprises one or more vias to couple traces within different layers.
43. (New) The electronic system recited in claim 26, wherein the film comprises one or more vias coupled to corresponding ones of the traces.